DEFENSE LOGISTICS AGENCY
WEAPONS SUPPORT
POST OFFICE BOX 3990
COLUMBUS, OH 43218-3990

July 21, 2026

Mike McCullar
Vice President, Quality
onsemi
5701 N Pima Road
Scottsdale, Arizona 85250

Dear Mr. McCullar:

Re: Full Certification Class Q and N for MIL-PRF-38535; FSC 5962; VQC-26-040412; Yu. Control Number:095703.

onsemi has demonstrated to the DLA Weapons Support compliance with MIL-PRF-38535, the QML specification used by the Department of Defense (DoD) for integrated circuits that operate in severe environments.

This DLA Weapons Support - VQC-26-040412 letter reflects the current certification status of onsemi as documented in the Quality System Manual (QSM) #12MQM97077A, Rev. CH, dated 03 June 2026.

In addition, the parts that are manufactured using the certified technology flows are being listed on the QML-38535. This will allow onsemi to mark parts with "QML" or "Q". These designators have been authorized by the DoD for parts that have been produced to a QML specification (i.e., one which allows less government oversight), the use of world-wide commercial production lines, reduced finished product testing based on statistical process control (SPC), and other cost advantages.

Testing must be performed using the facilities and methods listed in the Laboratory Suitability letter VQC-26-040413 or at facilities approved by the onsemi Technical Review Board or BU-CAB using its MIL-PRF-38535 QML Processing Program.

This certification is subject to the conditions in DoD 4120.24-M, Defense Standardization Program and SD-6.

All of the facilities mentioned on the enclosure are subject to an audit by the Qualifying Activity at any time. Offshore facilities are subject to the conditions of MIL-PRF-38535. The QML manufacturer is responsible for arranging for the qualifying activity to gain access to all applicable manufacturing facilities to perform site assessments to MIL-PRF-38535 requirements.

QPL/QML manufacturers shall notify the qualifying activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory or major quality/reliability problem on their QPL/QML products. Failure to provide prior notification may be grounds for removal from QML-38535.

In addition, it is requested that the following activities be reported promptly to DLA Weapons Support:

1. Changes to certified facilities, process flows, or approved testing subcontractors
2. Problem evaluation and a corrective action when:
   a. A Technology Conformance Inspection (TCI) failure has been validated
   b. The reliability of shipped parts is questionable.
3. Test optimization, including:
   a. Implementation - paragraph J.3.12, Appendix J, MIL-PRF-38535
   b. Changing, suspending or canceling a prior test optimization
4. Additions or deletions of parts in the QML-38535
5. Change of company QML contact or other key QML personnel

This certification is valid until terminated by written notice from DLA Weapons Support, and, if warranted, may be withdrawn at any time.

If you have any questions, please contact Mr. Shing Yu at (614) 693-0176.

Sincerely,

ADAMS.MICHAEL.S.1230230427

Digitally signed by ADAMS.MICHAEL.S.1230230427
Date: 2026.07.28 08:30:16 -04'00'

MICHAEL S. ADAMS
Chief
Custom Devices Branch

ENCLOSURE

Visit us on the web at: ***https://landandmaritimeapps.dla.mil/Offices/Sourcing_and_Qualification/default.aspx***

Enclosure to DLA Weapons Support - VQC-26-040412

| OPERATION | FACILITY | LOCATION | TECHNOLOGY | LINE / FLOW # |
|---|---|---|---|---|
| **Wafer Fab** | onsemi Gresham | Gresham, OR | 180nm CMOS | WH50_000001_01 |
| **Design** | onsemi Allen | Allen, TX | Custom ASICs | 12MQE00004A |
| **Mask Fab** | Controlled by Wafer Fab | Gresham, OR | Custom ASICs | 12MID7619107 |
| **Hermetic Assembly** | Integra Technologies Silicon Valley | Milpitas, CA | Ceramic Packages | 12MID7020040 |
| | Kyocera America, Inc. | San Diego, CA | DBGA Ceramic | 12MID7020040 |
| **Plastic Assembly** | Amkor/Anam (P1) | Manila, Philippines | LQFP | 12MID7020037 |
| | Amkor/Anam (P1) | Manila, Philippines | PLCC & PQFP (Residual Inventory) | 12MID7020037 |
| | Amkor/Anam (P3) | Laguna, Philippines | PBGA & chip carrier (Residual Inventory) | 12MID7020062<br>12MID7020037 |
| | Amkor (K4) | Gwangju, Korea | PBGA and FCBGA (Residual Inventory) | 12MID7020062<br>12MID7020037 |
| | Advanced Semiconductor Engineering, Inc. | Kaohsiung, Taiwan | PBGA, FCBGA, PQFP and LQFP | 12MID7020037 |
| **Die Attach Materials** | Integra Technologies Silicon Valley | Milpitas, CA | Eutectic and JM7000 | 12MID7020040 |
| | Kyocera America, Inc. | San Diego, CA | Eutectic and JM7000 | 12MID7020040 |
| **Wire Type and Wire Size** | Amkor/Anam | Manila, Philippines | Gold: 1 mil | 12MID7020037 |
| | Integra Technologies Silicon Valley | Milpitas, CA | Aluminum: 1.25 mil<br>Gold: 1 mil | 12MID7020040 |
| | Kyocera America, Inc. | San Diego, CA | Aluminum: 1.25 mil<br>Gold: 1 mil | 12MID7020040 |
| **Lid Seal** | Amkor/Anam | Manila, Philippines | Solder Furnace Seal | 12MID7020040 |
| | Integra Technologies Silicon Valley | Milpitas, CA | Solder Furnace Seal | 12MID7020040 |
| | Kyocera America, Inc. | San Diego, CA | Solder Furnace Seal | 12MID7020040 |
| **Lead Finish** | Criteria Labs for Hot Solder | Austin, TX | Hot Solder, Gold Plate, Tin-Lead Plate, Gold Flash Palladium | 12MID7050013<br><br>12MID7020037 |
| **Electrical Test** | onsemi Carmona | Carmona Cavite, Philippines | Custom ASICs | 12MID7050013<br>12MID7050026 |
| **Test/Screen/TCI** | See DLA Weapons Support -VQC-26-040413 QML Laboratory Suitability letter | | | |
| **Hermetic Package Technology** | Chip Carrier (pre-J up to 84 leaded)<br>Chip Carrier (leadless up to 84 terminals)<br>Flat Pack (100-352 leads)<br>Side-braze (28-48 leads)<br>Pin Grid Array (69-181 pins)<br>DBGA (228-277 balls) | | | |
| **Plastic Package Technology** | Flat Pack (44-240 leads)<br>Chip Carrier (28-84 leads)<br>LFPBGA (84 balls max)<br>BGA (564 balls max)<br>SBGA (560 balls max) | | | |